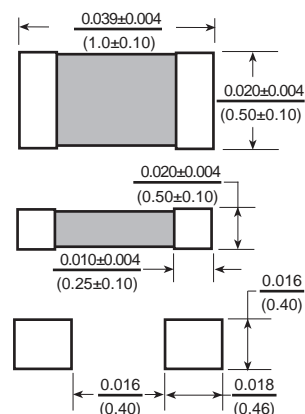




Dimensions: $\frac{\text{Inches}}{\text{(mm)}}$



Allied Part Number	Impedance (Ω) @ 100 MHz +/- 25%	DC Resistance (Ω) Max.	*Rated Current (mA)
MLB03-060-RC	6	0.05	500
MLB03-100-RC	10	0.05	500
MLB03-300-RC	30	0.30	300
MLB03-330-RC	33	0.30	300
MLB03-400-RC	40	0.30	300
MLB03-470-RC	47	0.40	300
MLB03-600-RC	60	0.40	300
MLB03-700-RC	70	0.40	300
MLB03-750-RC	75	0.40	300
MLB03-800-RC	80	0.40	300
MLB03-900-RC	90	0.50	300
MLB03-101-RC	100	0.50	300
MLB03-121-RC	120	0.50	300
MLB03-151-RC	150	0.50	300
MLB03-221-RC	220	0.50	300
MLB03-241-RC	240	0.50	300
MLB03-301-RC	300	0.80	300
MLB03-331-RC	330	0.80	300
MLB03-481-RC	480	0.80	300
MLB03-601-RC	600	1.00	300
MLB03-102-RC	1000	1.50	100
MLB03-152-RC	1500	2.00	60

*Temperature rise $\Delta T=30^{\circ}\text{C}$ at rated current.
All specifications subject to change without notice.

Features

- Surface mount EMI suppression components
- Nickel barrier termination for excellent resistance to solder heat
- Multi layer technology
- Flow and reflow soldering

Electrical

Impedance Range: 6 Ω to 1500 Ω

Tolerance: 25% over entire range

Operating Range: -55 $^{\circ}\text{C}$ ~ +125 $^{\circ}\text{C}$

Storage Temp: Under 25 $^{\circ}\text{C}$ at 40~60% Humidity

Rated Current: Based on temp rise not to exceed 30 $^{\circ}\text{C}$

Resistance to Solder Heat

Pre-Heat 150 $^{\circ}\text{C}$, 1 minute

Solder Composition: Sn/Ag3.0/Cu0.5

Solder Temp: 260 \pm 5 $^{\circ}\text{C}$ for 10sec \pm 1 sec.

Minimum of 75% of Electrode covered with new solder.

Impedance within 30% of initial value.

Test Equipment

(Z): HP4291A RF Impedance/Material Analyzer

(RDC): Chen Hwa 502BC

Physical

Packaging: 10000 per 7 inch reel.

Marking: None